

/ Descriptions

KF \$0) E GE Silicon NPN transistor in a TO-92 Plastic Package.

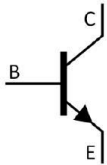
/ Features

)JB(' - /
low saturation voltage, high DC current gain, high total power dissipation P_C Complementary pair with 2SB1068.

/ Applications

For use in driver and output stages of audio frequency amplifiers.

/ Equivalent Circuit



/ Pinning



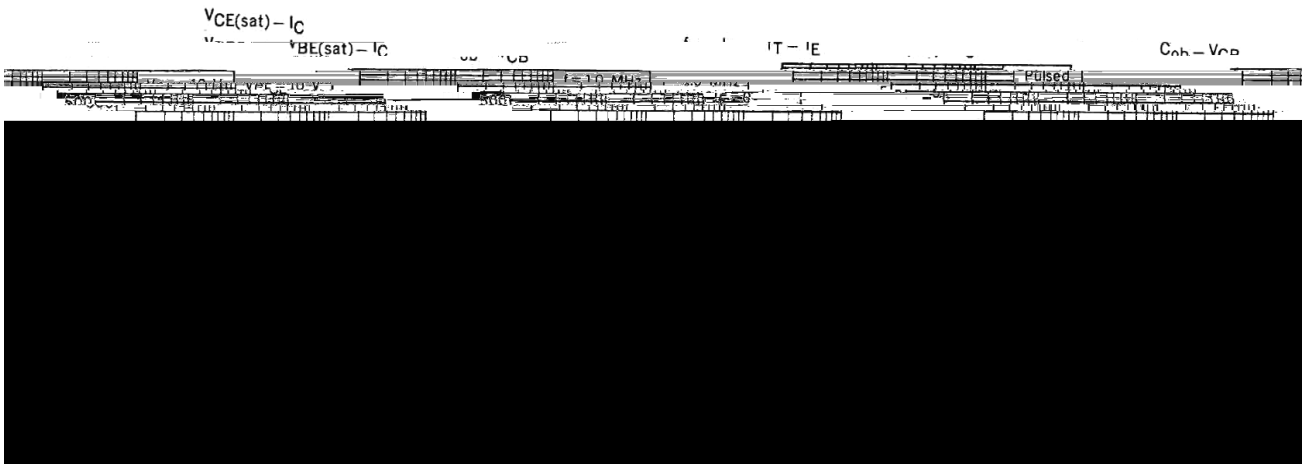
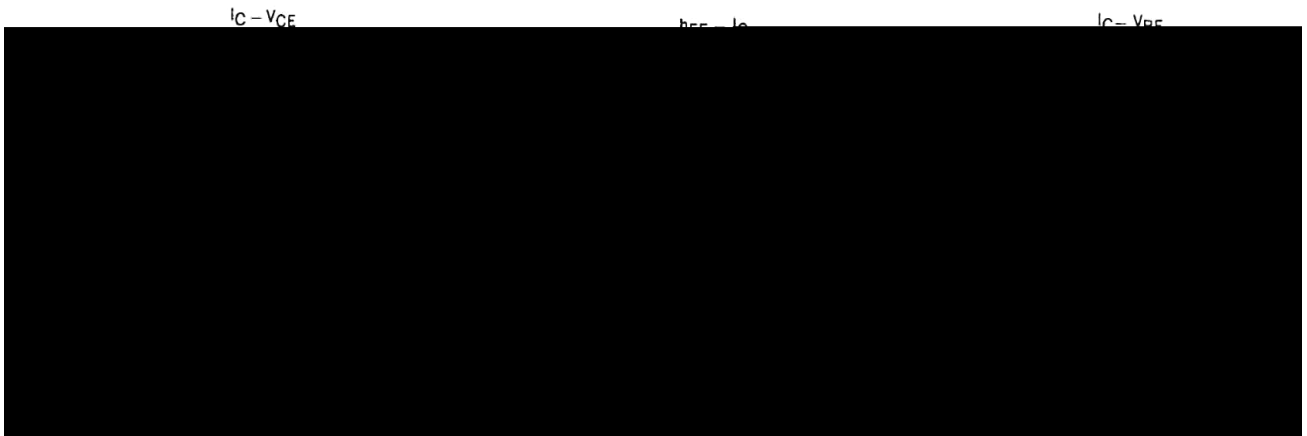
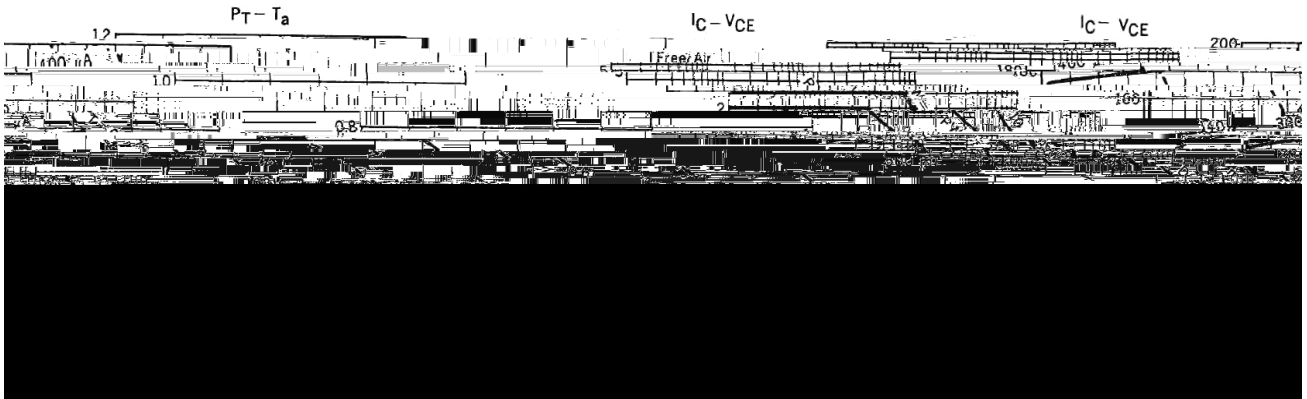
PIN1 Base PIN 2 Collector PIN 3 Emitter

/ hFE Classifications & Marking

h _{FE} Classifications Symbol	L	K	U
h _{FE} Range	135~270	200~400	300~650

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	20	V
Collector to Emitter Voltage	V_{CEO}	16	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current - Continuous	I_C	2.0	A
Collector Current – Continuous(Pulse)	I_{CP}	3.0	A
Collector Power Dissipation	$P_C(T_a=25 \text{ } ^\circ\text{C})$	750	mW

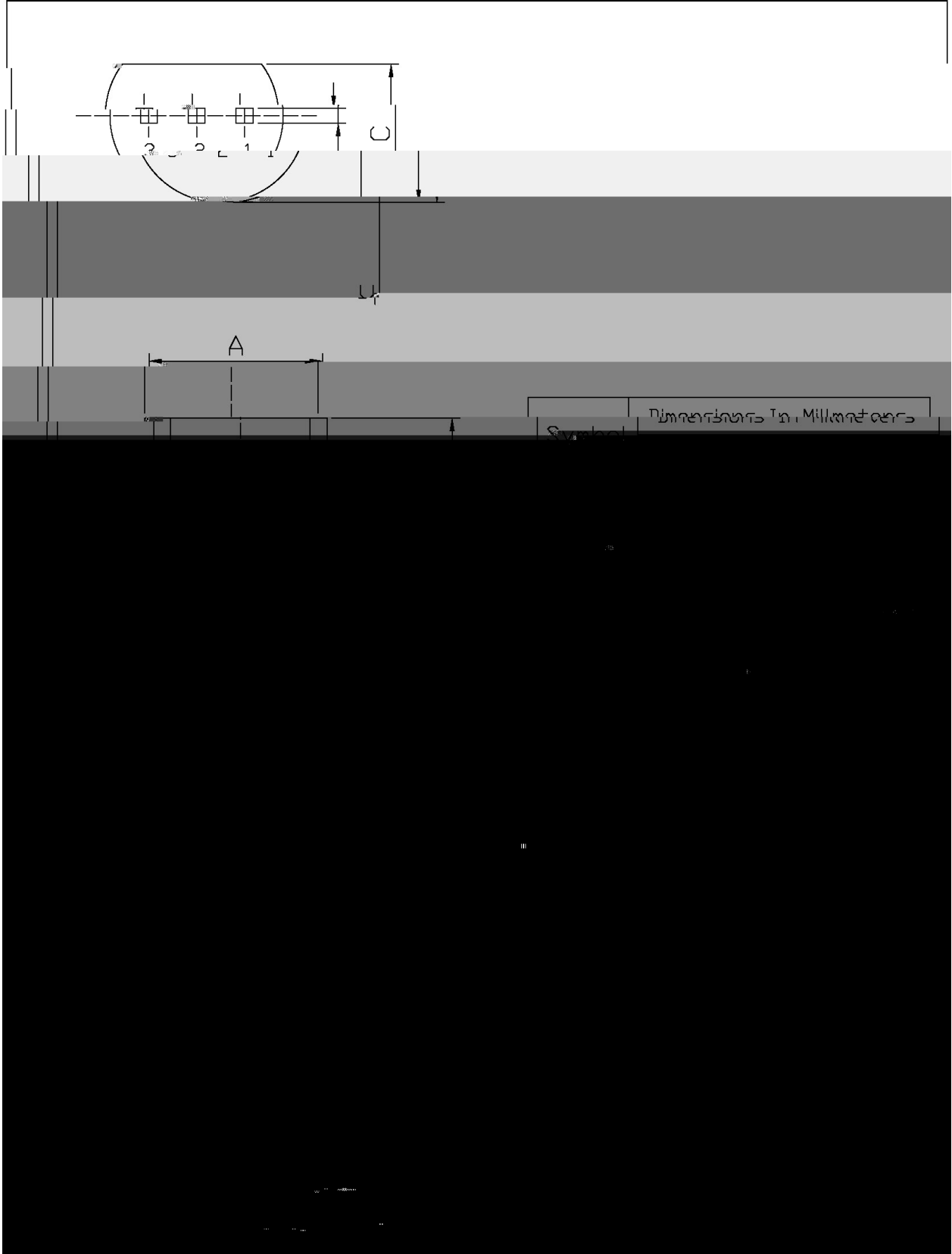
/ Electrical Characteristic Curve



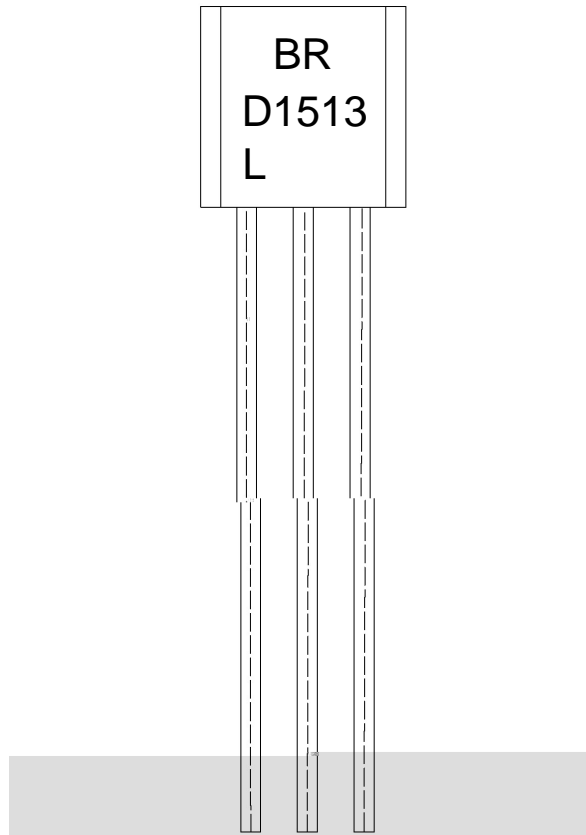
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



BI 1

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L1 h_{FE}

Note:

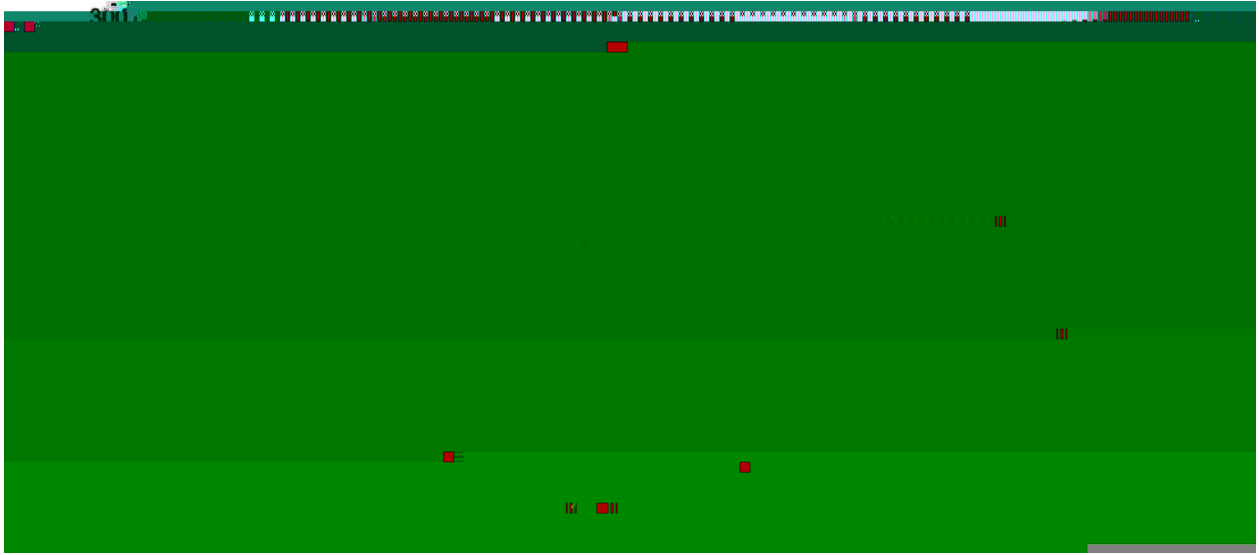
BR: Company Code.

D1513: Product Type.

L: h_{FE} Classifications Symbol

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	只纸带	纸带盒	纸带层盒	盒箱	只箱	盒	箱
						小箱	大箱

/ Notices